

L Number	Hits	Search Text	DB	Time stamp
1	2	(underfill\$3 adhesives seal\$4) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 filler\$1 powder\$1) same (curing hardening) adj agent\$1	USPAT; US-PGPUB; EPO; JPO	2004/04/30 12:56
2	2	((underfill\$3 adhesives seal\$4) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 filler\$1 powder\$1) same (curing hardening) adj agent\$1) and (underfill\$3 adhesives seal\$4) same (curing hardening) adj agent\$1	USPAT; US-PGPUB; EPO; JPO	2004/04/30 12:55
3	17	(underfill\$3 adhesives seal\$4) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 filler\$1 powder\$1) same (curing hardening)	USPAT; US-PGPUB; EPO; JPO	2004/04/30 12:57
4	17	((underfill\$3 adhesives seal\$4) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 filler\$1 powder\$1) same (curing hardening)) and (underfill\$3 adhesives seal\$4) same (curing hardening)	USPAT; US-PGPUB; EPO; JPO	2004/04/30 12:57
-	57	underfill\$3 adj (composition mixture\$1 paste slurry)	USPAT; US-PGPUB; EPO; JPO	2004/04/27 16:44
-	6	((("6356333") or ("20020127406") or ("5128746") or ("6063647") or ("6168972") or ("6260264")).PN.	USPAT; US-PGPUB; EPO; JPO	2004/04/26 12:34
-	17	(underfill\$3 adhesives) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 grain\$1 ball\$1 filler\$1 powder\$1)	USPAT; US-PGPUB; EPO; JPO	2004/04/27 16:47
-	17	((underfill\$3 adhesives) adj (composition mixture\$1 paste slurry) same (solder metal\$4) near5 (particle\$1 grain\$1 ball\$1 filler\$1 powder\$1)) and (underfill\$3 adhesives) same (solder metal\$4)	USPAT; US-PGPUB; EPO; JPO	2004/04/30 12:51